



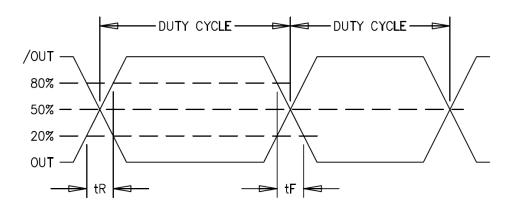
Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		50.000000		MHz	
		Fre	equency Sta	bility		
Frequency Stability	ΔF/F	-50		+50	ppm	Includes initial tolerance @ +25°C, deviation over operating temperature, variations to supply voltage, load, vibration, shock and aging.
Aging		-5		+5	ppm	1 st year
			RF Outpu	t		
Output Type		LV	PECL Compa	tible		
Output Load		50	Ω to (Vcc-2.0)	VDC	V	
Symmetry (duty cycle)	Vон	45	50	55	%	Ref. to 50% of waveform
Logic Level "1"	Voh	Vcc-1.025			V	
Logic Level "0"	T _{DC}			Vcc-1.620	V	
Rise/Fall Time	T _R /T _F			1.0	ns	20% to 80% of waveform
Enable Logic		70% V _{CC} or N/C			V	Pad 1: Output Enabled
Disable Logic				30% Vcc	V	Pad 1: Output Disabled to high-Z
Start-up Time	Tsu			10	ms	T _{ambient} = +25°C
	S	upply Volta	age & Powe	r Consumpt	ion	
Operating Voltage	Vcc 3.135 3.3 3.465			V		
Supply Current	Icc			60	mA	
			Other Parame	ters		
Phase Jitter (RMS)	ФЈ			1.00	pS	12 KHz to 20 MHz





Output Waveform:



Environmental & Packaging Requirements:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Operating Temperature	TA	-40		+85	°C	
Storage Temperature	Ts	-55		+125	°C	
Mechanical Shock	Per MIL-STI	D-202, Meth	od 213, Coi	ndition C (100	g's, 6 ms	duration, ½ sinewave)
Vibration	Per MIL-STI	D-202, Meth	od 201 & 20	04 (10 g's from	10-2000	Hz)
Thermal Cycle	Per MIL-STI	D-883, Meth	od 1010, B	(-55°C to 125°	°C, 15 mir	ı. dwell, 10 cycles)
Hermeticity	Per MIL-STI	D-202, Meth	od 112 (1 x	10 ⁻⁸ atm cc/s	of Helium)
Moisture Sensitivity Level (MSL)	MSL 1					
Solderability	Per EIAJ-ST	ΓD-002				
Max. Soldering Conditions	See solder	orofile, Figur	e 1.			
Package Type	2.50 mm (typ) X 3.20 mm (typ) X 1.10 (max) mm 6-pad leadless ceramic. RoHS compliant.					





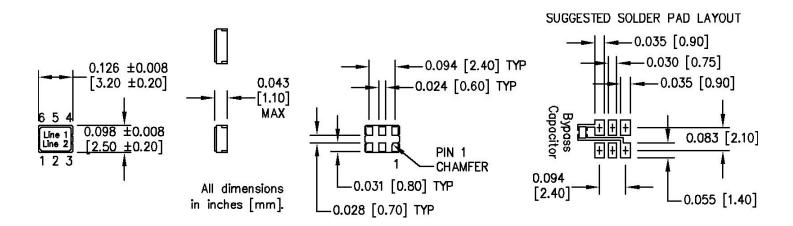
Marking, Pin Out:

Pad	Function
Fau	i unction
1	Enable/Disable
2	N/C
3	Ground
4	Output
5	Complementary Output
6	+V _{cc}

Part Marking				
Line 1	50M0000			
Line 2	M yy ww vv			

Legend				
уу	yy Year			
ww	Work week			
VV	Factory code			

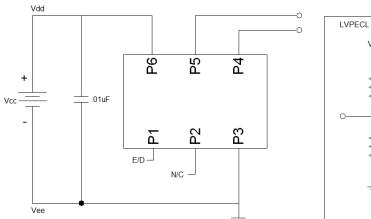
Dimensions:

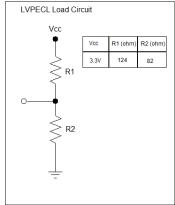






Typical Test Circuit & Load Circuit Diagrams:





Soldering Conditions:

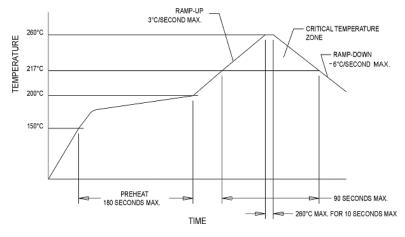


Figure 1

Datasheet Revision Table:

Date	Rev.	Author	Details of Revision
12/15/17	0	MM	Original release.